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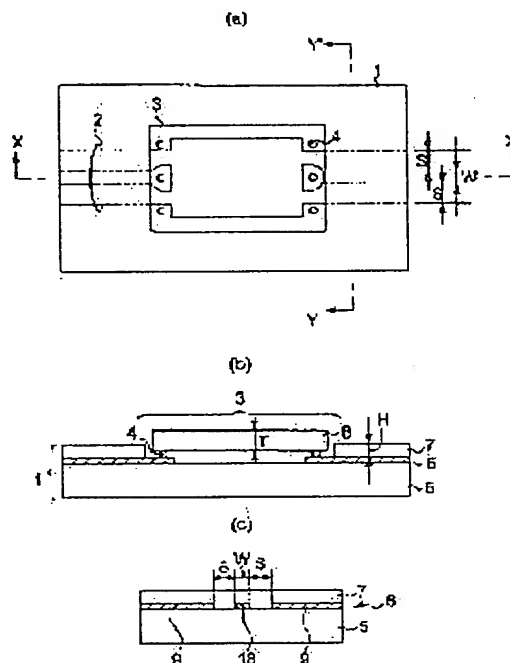
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(54) HIGH-FREQUENCY CIRCUIT BOARD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a high-frequency circuit board which relaxes the size of a minimum line width/an interval required by a coplanar line at a small distance to a ground, which is low-cost and whose yield is high in the high-frequency circuit board on which the coplanar line is formed.

SOLUTION: In this high-frequency circuit board 1, a first dielectric layer 5, a conductor layer 6 and a second dielectric layer 7 are laminated in this order and are formed. A coplanar line 2 is formed on the conductor layer 6. A region, in which a semiconductor element 8 is mounted out of the second dielectric layer 7, is partially removed, and an opening part 3 is formed. In the opening part 3, the coplanar line 2 is partially exposed, and bumps 4 are formed. The semiconductor element 8 is connected via the bumps 4 to the coplanar line, which is formed on the conductor layer 6. A thickness H of the second dielectric layer is smaller than a thickness T of the semiconductor element 8.



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